

(1)

wherein n is 0 or a positive integer,

and the curing accelerator comprises (i) a compound having a catalytic function to accelerate the curing reaction of the said cyanate type compound (A) and (ii) a compound having a catalytic function to accelerate the curing reaction of the epoxy resin,

wherein the epoxy resin (B) is contained in an amount of 50 to 250 parts by weight, the curing accelerator (C) is contained in an amount of 0.1 to 5 parts by weight and the antioxidant (D) is contained in an amount of 0.1 to 20 parts by weight per 100 parts by weight of said cyanate type compound (A).

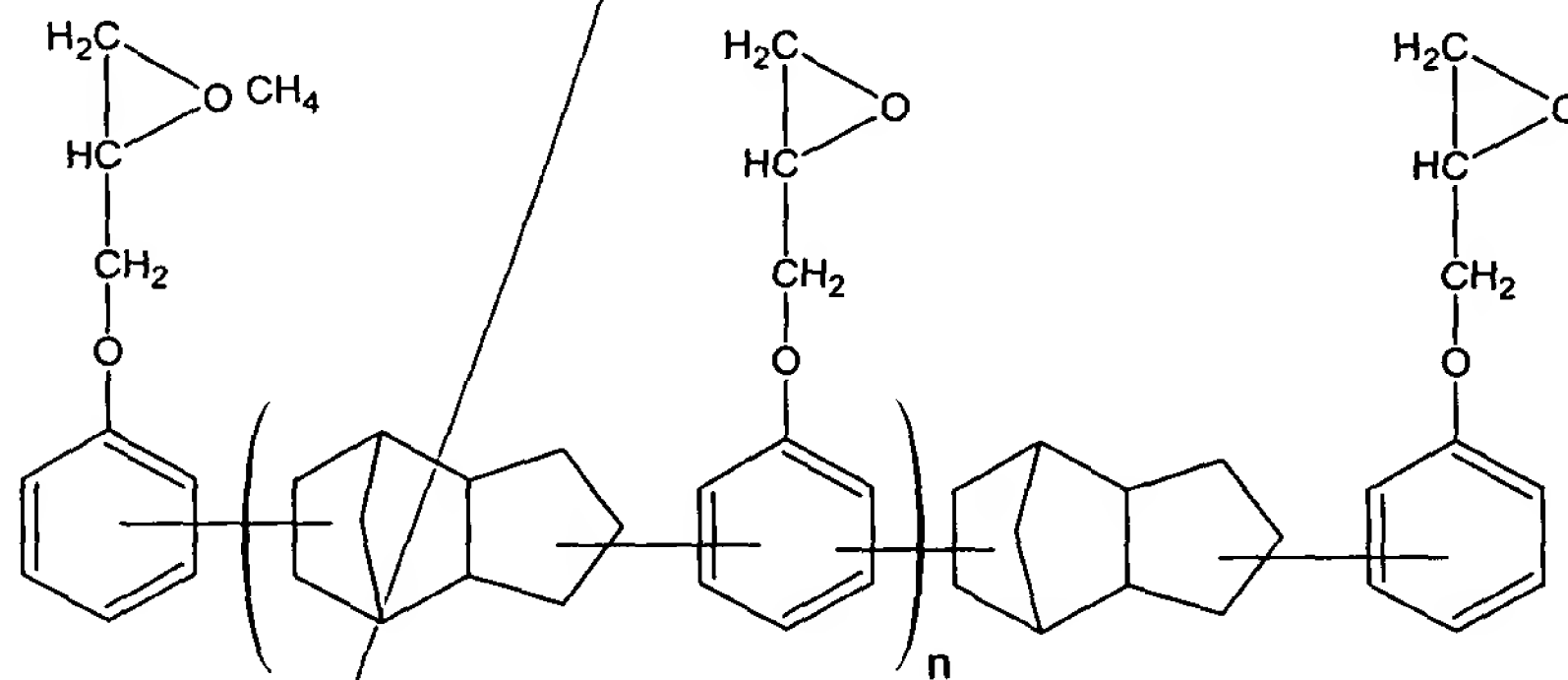
10. (Amended) A cyanate-epoxy resin composition according to Claim 1, wherein the compound having a catalytic function to accelerate the curing reaction of the cyanate type compound (A) is at least one of the organic metal salts or organic metal complexes of one or more of the metals selected from iron, copper, zinc, cobalt, nickel, manganese and tin, and the compound having a catalytic function to accelerate the curing reaction of the epoxy resin (B) is at least one compound

a4 selected from imidazole and its derivatives, organic phosphorus compounds, secondary amines, tertiary amines and quaternary ammonium salts.

Please add new Claims 11 - 16 as follows:

- 11. A prepreg obtained by impregnating a cyanate-epoxy resin comprising
- (A) a cyanate compound containing two or more cyanato groups in one molecule thereof in an amount of 100 parts by weight,
 - (B) an epoxy resin in an amount of 50 to 250 parts by weight,
 - (C) a curing accelerator in an amount of 0.1 to 5 parts by weight, and
 - (D) an antioxidant in an amount of 0.1 to 20 parts by weight, as main components,
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a5 wherein the epoxy resin (B) is derived from a dicyclopentadiene-phenol polyaddition product having a dicyclopentadiene skeleton represented by the following formula (1):



wherein n is 0 or a positive integer, and the curing accelerator comprises (i) a compound (C) having a catalytic function to accelerate the curing reaction of said cyanate type compound (A) and (ii) a compound having a catalytic function to accelerate the curing reaction of said epoxy resin (B),

in a base, and drying the same.

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12. A prepreg according to claim 11, wherein the compound having a catalytic function to accelerate the curing reaction of said cyanate type compound (A) is an organic metal salt or an organic metal complex, and the compound having a catalytic function to accelerate the curing reaction of the epoxy resin (B) is an imidazole compound.

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13. A prepreg according to claim 12, wherein the organic metal salt or the organic metal complex is an organic metal salt or an organic metal complex of iron, copper, zinc, cobalt, nickel, manganese or tin.

14. A metal foil-laminated plate obtained by laminating a metal foil on one side or both sides of the prepreg of Claim 11 or a laminate thereof, and subjecting the laminate to hot-press molding.

15. A printed wiring board obtained by conducting a circuit-forming work on the metal foil of the metal foil-laminated plate of Claim 14.

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16. A prepreg according to Claim 11, wherein the compound having a catalytic function to accelerate the curing reaction of the cyanate type compound (A)

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is at least one of the organic metal salts or organic metal complexes of one or more of the metals selected from iron, copper, zinc, cobalt, nickel, manganese and tin, and the compound having a catalytic function to accelerate the curing reaction of the epoxy resin (B) is at least one compound selected from imidazole and its derivatives, organic phosphorus compounds, secondary amines, tertiary amines and quaternary ammonium salts.
